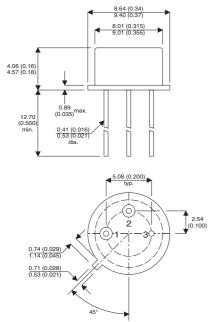


2N6794





# **N–CHANNEL ENHANCEMENT MODE POWER MOSFET**

$BV_{DSS}$	500V
I <sub>D(cont)</sub>	1.5
R <sub>DS(on)</sub>	<b>3.0</b> Ω

### **FEATURES**

- AVALANCHE ENERGY RATED
- HERMETICALLY SEALED
- DYNAMIC dv/dt RATING
- SIMPLE DRIVE REQUIREMENTS

**Underside View** Pin 1 – Source Pin 2 – Gate Pin 3 – Drain

TO39 – Package (TO-205AF)

### ABSOLUTE MAXIMUM RATINGS (T<sub>case</sub> = 25°C unless otherwise stated)

V <sub>GS</sub>	Gate – Source Voltage	±20V		
I <sub>D</sub>	Continuous Drain Current $(V_{GS} = 10V, T_{case} = 25^{\circ}C)$	1.5A		
I <sub>D</sub>	Continuous Drain Current $(V_{GS} = 10V, T_{case} = 100^{\circ}C)$	1A		
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup>	6.5A		
P <sub>D</sub>	Power Dissipation @ T <sub>case</sub> = 25°C	20W		
	Linear Derating Factor	0.16W/°C		
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>2</sup>	0.11mJ		
dv/dt	Peak Diode Recovery <sup>3</sup>	3.5V/ns		
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range	–55 to 150°C		
$R_{\theta JC}$	Thermal Resistance Junction to Case	6.25°C/W		
$R_{ extsf{ heta}JA}$	Thermal Resistance Junction-to-Ambient	175°C/W		

#### Notes

1) Pulse Test: Pulse Width  $\leq$  300 $\mu$ s,  $\delta \leq$  2%

2) @ V\_DD = 50V , L  $\geq$  0.100mH , R\_G = 25 $\Omega$  , Peak I\_L = 1.5A , Starting T\_J = 25°C

3) @ I\_{SD}  $\leq$  1.5A , di/dt  $\leq$  50A/ $\mu s$  , V\_{DD}  $\leq$  BV\_{DSS} , T\_J  $\leq$  150°C , SUGGESTED R\_G = 7.5  $\Omega$ 

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## ELECTRICAL CHARACTERISTICS (Tamb = 25°C unless otherwise stated)

	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
	STATIC ELECTRICAL RATINGS	1		1			1
BV <sub>DSS</sub>	Drain – Source Breakdown Voltage	$V_{GS} = 0$	I <sub>D</sub> = 1mA	500			V
$\Delta BV_{DSS}$	Temperature Coefficient of	Reference to 25°C					1/100
$\Delta T_{J}$	Breakdown Voltage	I <sub>D</sub> = 1mA			0.43		V/°C
R <sub>DS(on)</sub>	Static Drain – Source On–State	$V_{GS} = 10V$	I <sub>D</sub> = 1A			3	
	Resistance	$V_{GS} = 10V$	I <sub>D</sub> = 1.5A			3.45	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250μA	2		4	V
9 <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V	I <sub>DS</sub> = 1A	1		3	S(ଫ)
	Zero Gate Voltage Drain Current	$V_{GS} = 0$	$V_{DS} = 0.8BV_{DSS}$			25	μΑ
IDSS			T <sub>J</sub> = 125°C			250	
I <sub>GSS</sub>	Forward Gate - Source Leakage	$V_{GS} = 20V$				100	- n A
I <sub>GSS</sub>	Reverse Gate – Source Leakage	$V_{GS} = -20V$				-100	nA
	DYNAMIC CHARACTERISTICS	1					
C <sub>iss</sub>	Input Capacitance	$V_{GS} = 0$			350		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V			80		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1MHz	-		35		
		V <sub>GS</sub> = 10V	I <sub>D</sub> = 1.5A	7.0		167	
Qg	Total Gate Charge	$V_{DS} = 0.5 BV_{DS}$		7.3		16.7	nC
Q <sub>gs</sub>	Gate – Source Charge	I <sub>D</sub> =1.5A		0.1		3	nC
Q <sub>gd</sub>	Gate – Drain ("Miller") Charge	$V_{DS} = 0.5BV_{DS}$		3.7		8.7	
t <sub>d(on)</sub>	Turn–On Delay Time	V 050V			4	40	- ns
t <sub>r</sub>	Rise Time	$V_{DD} = 250V$				30	
t <sub>d(off)</sub>	Turn–Off Delay Time	$I_{\rm D} = 1.5A$				60	
t <sub>f</sub>	Fall Time	- R <sub>G</sub> = 7.5Ω	-			30	
	SOURCE - DRAIN DIODE CHARAC	TERISTICS					
I <sub>S</sub>	Continuous Source Current					1.5	
I <sub>SM</sub>	Pulse Source Current <sup>2</sup>					6.5	- A
		I <sub>S</sub> = 1.5A	$T_J = 25^{\circ}C$			1.0	V
	Diode Forward Voltage	$V_{GS} = 0$	-			1.2	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 1.5A	T <sub>J</sub> = 25°C			900	ns
Q <sub>rr</sub>	Reverse Recovery Charge	<sup>−</sup> d <sub>i</sub> / d <sub>t</sub> ≤ 100A/µs	s V <sub>DD</sub> ≤ 50V			5.9	μC
t <sub>on</sub>	Forward Turn–On Time				Negligible		
-	PACKAGE CHARACTERISTICS	1	I				1
L <sub>D</sub>	Internal Drain Inductance (from centre o	f drain pad to die)		5.0			
L <sub>S</sub>	Internal Source Inductance (from centre	re of source pad to end of source bond wire) 15.0					– nH
Notes	1) Pulse Test: Pulse Width $\leq$ 3					1	

2) Repetitive Rating - Pulse width limited by maximum junction temperature.

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